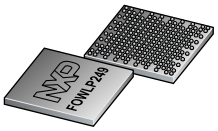


SOT2003-1

FOWLP249, fan-out wafer-level package, 249 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.725 mm body

15 September 2020 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FOWLP249
Package style descriptive code	FOWLP (fan-out wafer-level package)
Mounting method type	S (surface mount)
Issue date	17-06-2020
Manufacturer package code	98ASA01357D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.95	7	7.05	mm
package width	6.95	7	7.05	mm
seated height	-	0.725	0.76	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	249	-	

2 Package outline

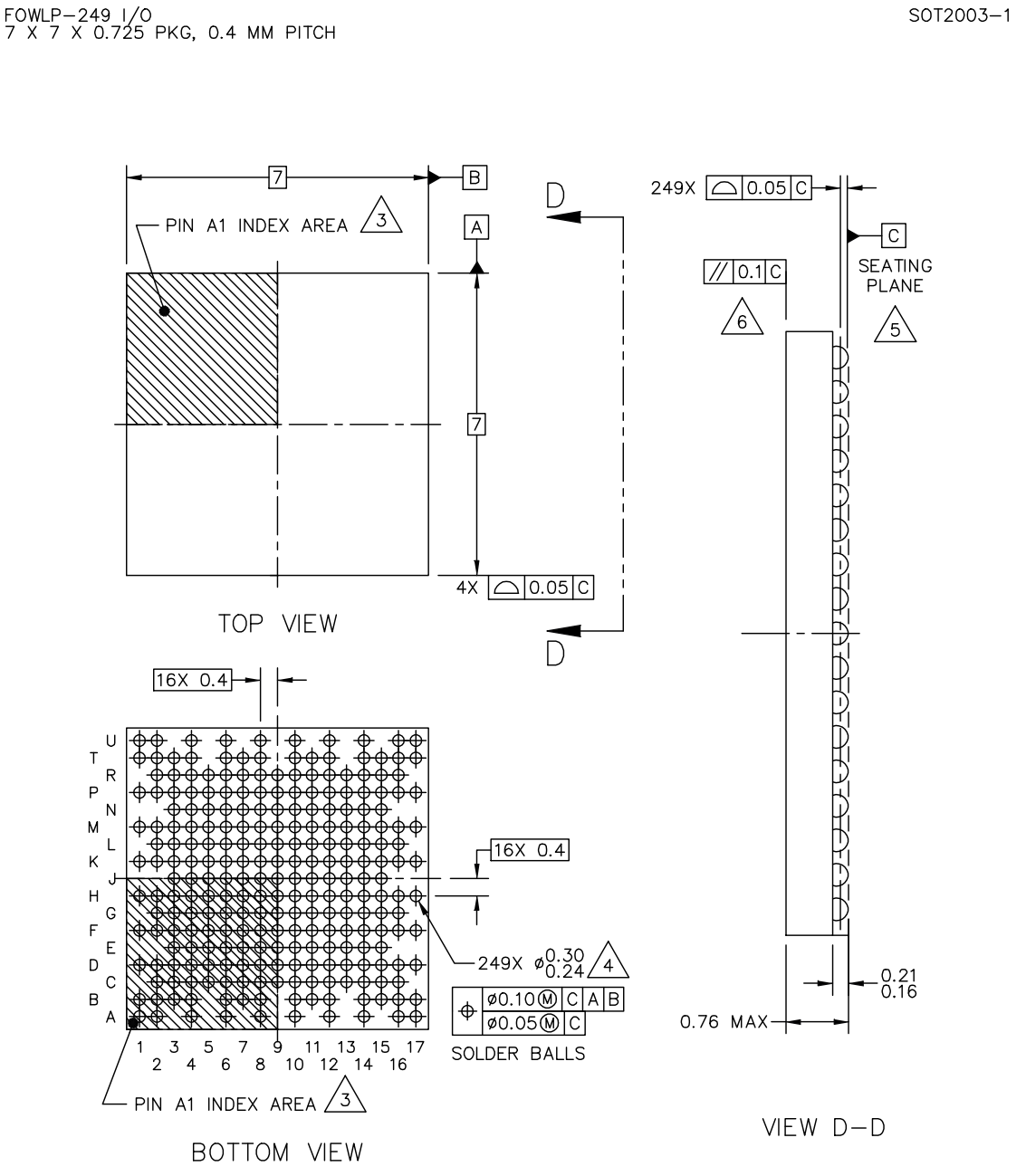


Figure 1. Package outline FOWLP249 (SOT2003-1)

3 Soldering

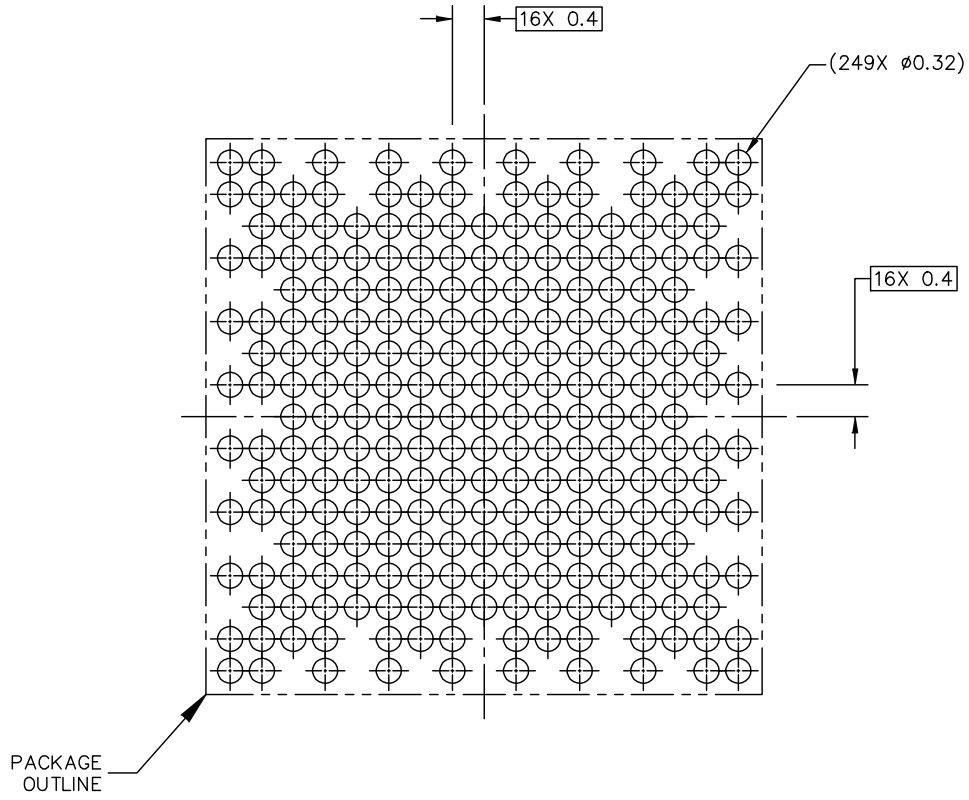


Figure 2. Reflow soldering footprint part1 for FOWLP249 (SOT2003-1)

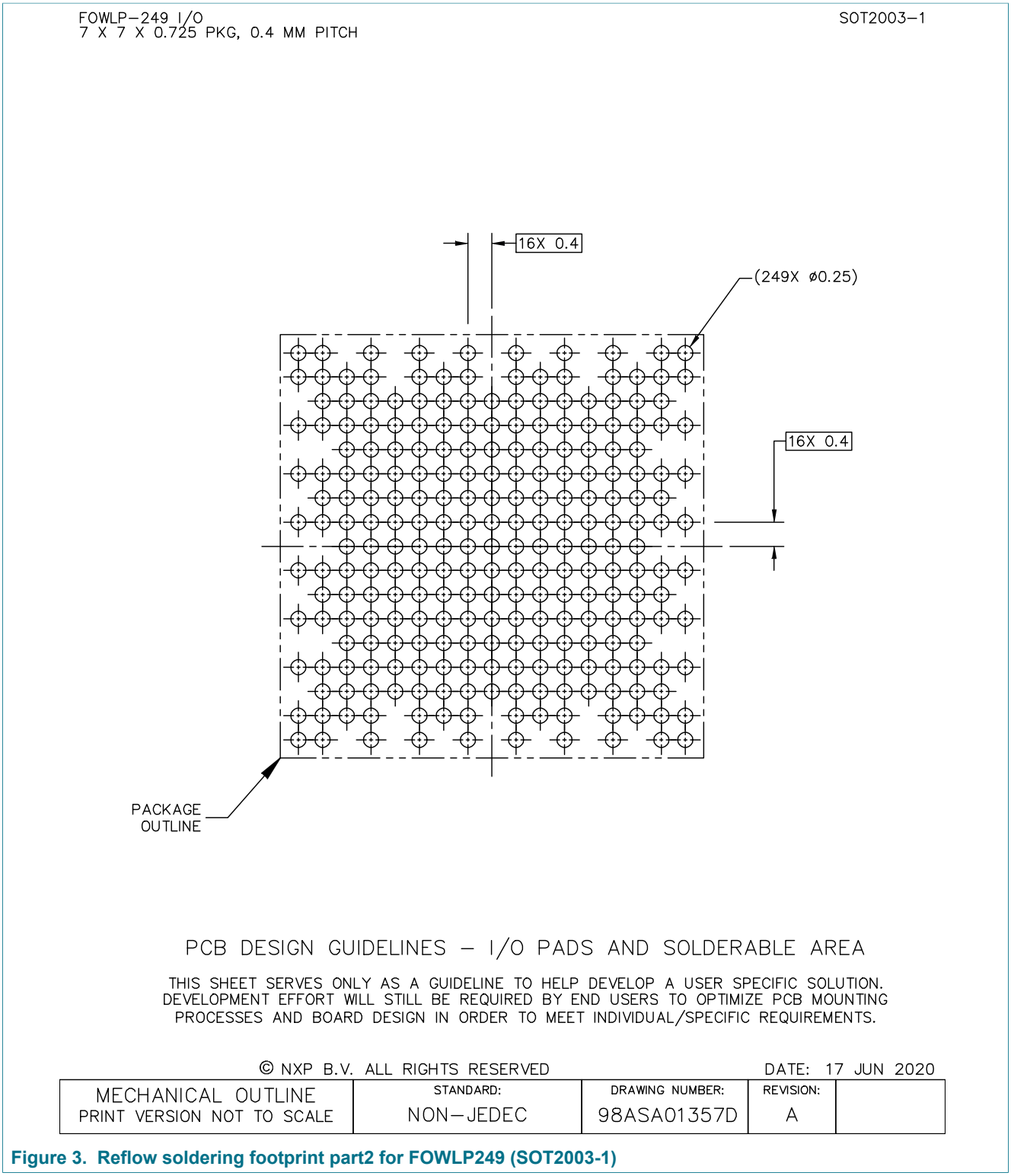
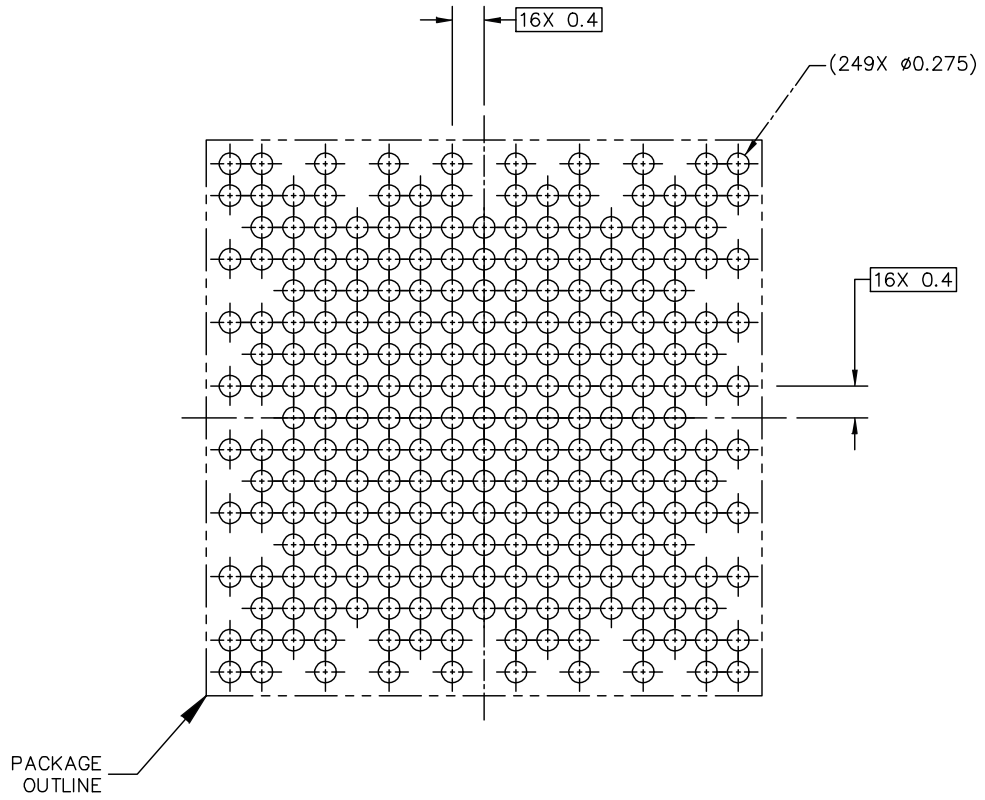


Figure 3. Reflow soldering footprint part2 for FOWLP249 (SOT2003-1)



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 17 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01357D	REVISION: A	

Figure 4. Reflow soldering footprint part3 for FOWLP249 (SOT2003-1)

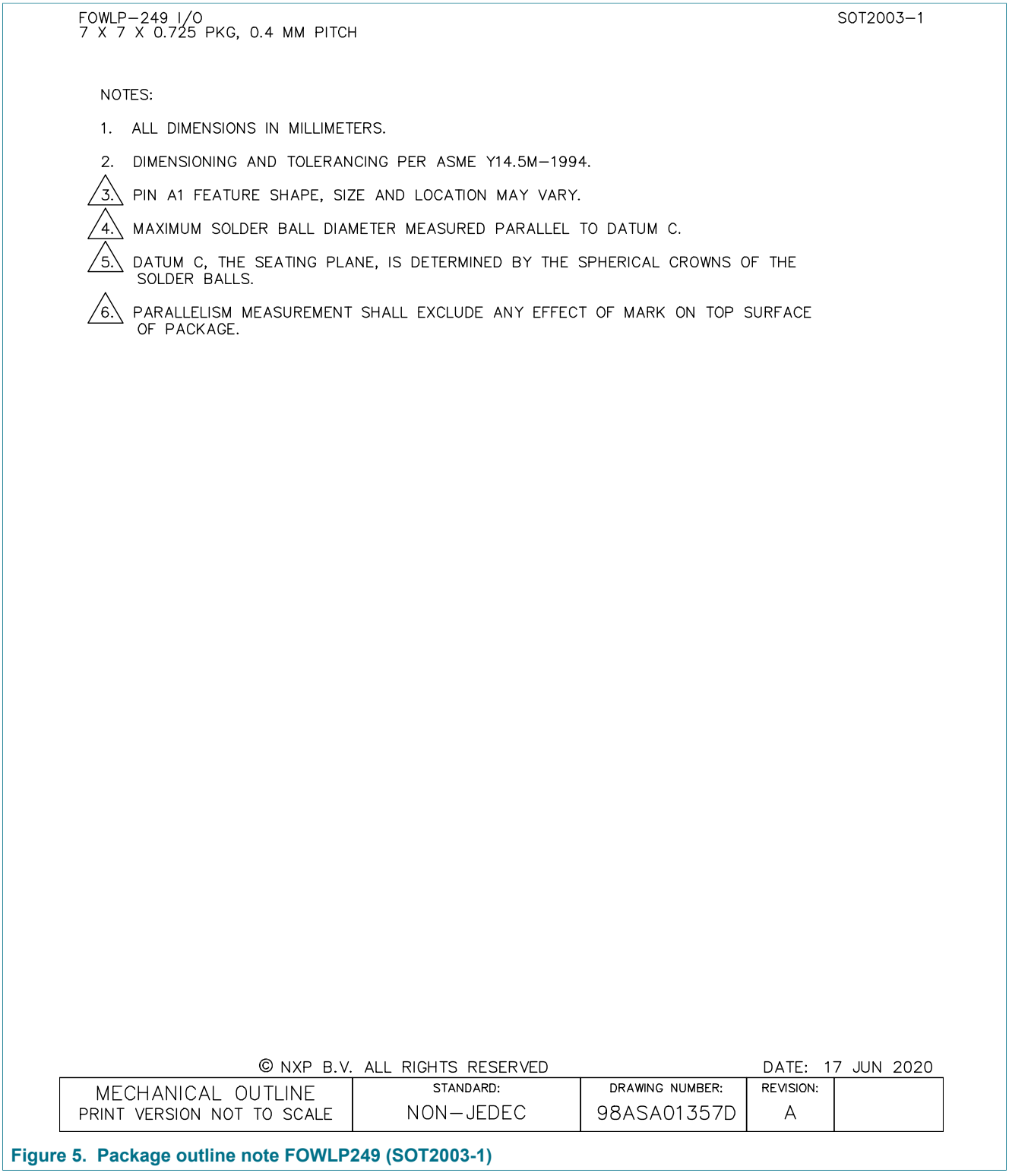

Figure 5. Package outline note FOWLP249 (SOT2003-1)

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FOWLP249, fan-out wafer-level package, 249 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.725 mm body

Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 15 September 2020